

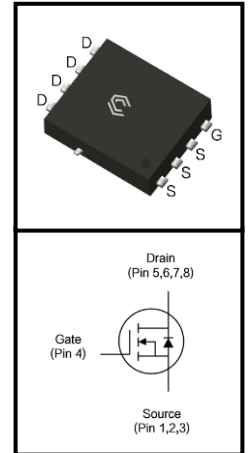
## 60V N-Channel MOSFET

### FEATURES

- Super Low Gate Charge
- 100% EAS Guaranteed
- RoHS compliant
- Green Device Available
- Excellent  $C^*dV/dt$  effect decline
- Advanced high cell density Trench technology

### APPLICATIONS

- Load Switching
- Hard switched and high frequency circuits
- Uninterruptible power supply



### Device Marking and Package Information

Device	Package	Marking
CSN06N2P8	PDFN5 × 6	CSN06N2P8

### Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage ( $V_{GS} = 0V$ )	$V_{DSS}$	60	V
Continuous Drain Current (note1)	$I_D$	140	A
Pulsed Drain Current (note2)	$I_{DM}$	560	A
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Single Pulse Avalanche Energy (note3)	$E_{AS}$	320.17	mJ
Avalanche Current (note3)	$I_{AS}$	29.4	A
Repetitive Avalanche Energy (note3)	$E_{AR}$	1.3	mJ
Power Dissipation ( $T_C = 25^\circ\text{C}$ )	$P_D$	108.4	W
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	$-55 \sim +150$	$^\circ\text{C}$

### Thermal Resistance

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (note4)	$R_{thJC}$	1.15	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	62.5	

**Specifications**  $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static						
Drain–Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	60	--	--	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 25°C	--	--	1	uA
Gate–Source Leakage	I <sub>GSS</sub>	V <sub>GS</sub> = ± 20V	--	--	± 100	nA
Gate–Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1.0	--	2.5	V
Drain–Source On–Resistance (note5)	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 30A	--	2.3	2.8	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 20A	--	3.0	3.6	mΩ
Dynamic						
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> =30V, f = 1.0MHz	--	3685	--	pF
Output Capacitance	C <sub>oss</sub>		--	1085	--	
Reverse Transfer Capacitance	C <sub>rss</sub>		--	33	--	
Gate Resistance	R <sub>g</sub>	V <sub>GS</sub> = 0V,f = 1MHz	--	3.2	--	Ω
Total Gate Charge	Q <sub>g</sub>	V <sub>DD</sub> = 48V, I <sub>D</sub> = 30A, V <sub>GS</sub> = 10V	--	64.7	--	nC
Gate–Source Charge	Q <sub>gs</sub>		--	6.7	--	
Gate–Drain Charge	Q <sub>gd</sub>		--	10.7	--	
Turn–on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =30V, I <sub>D</sub> = 30A, R <sub>G</sub> = 3Ω	--	14	--	ns
Turn–on Rise Time	t <sub>r</sub>		--	83	--	
Turn–off Delay Time	t <sub>d(off)</sub>		--	66	--	
Turn–off Fall Time	t <sub>f</sub>		--	41	--	
Drain–Source Body Diode Characteristics						
Continuous Body Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C	--	--	140	A
Pulsed Diode Forward Current	I <sub>SM</sub>		--	--	560	
Body Diode Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25°C, I <sub>SD</sub> = 30A, V <sub>GS</sub> = 0V	--	--	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	V <sub>DD</sub> = 30V,I <sub>S</sub> = 30A, di <sub>f</sub> /dt =100A / μ s	--	39	--	ns
Reverse Recovery Charge	Q <sub>rr</sub>		--	0.042	--	uC

**Notes**

- $I_D = 80\% I_{D-Max}$
- Repetitive Rating: Pulse width limited by maximum junction temperature
- $L = 0.5mH, V_{DD} = 30V, R_G = 25\Omega, E_{AS} = 60\% E_{AS-Max}, I_{AS} = 60\% I_{AS-Max}$ , Starting  $T_J = 25^{\circ}\text{C}$
- Reference standard for thermal resistance testing: JESD51-14
- Pulse Test: Pulse width  $\leq 300\mu s$ , Duty Cycle  $\leq 1\%$

Typical Characteristics  $T_J = 25^\circ\text{C}$ , unless otherwise noted

Figure 1. Output Characteristics

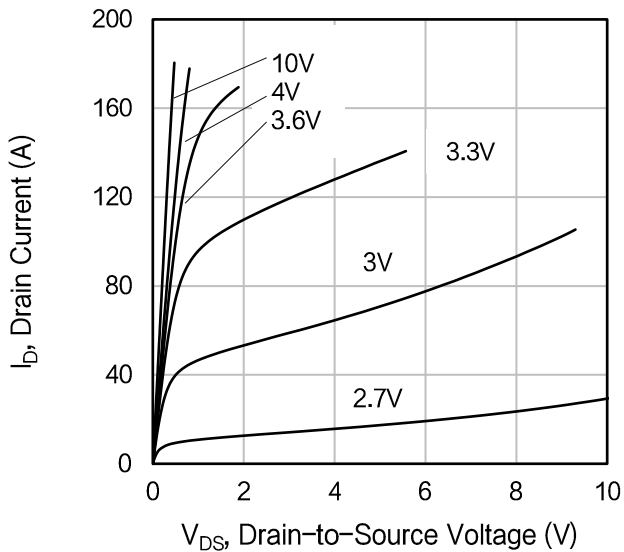


Figure 2. Body Diode Forward Voltage

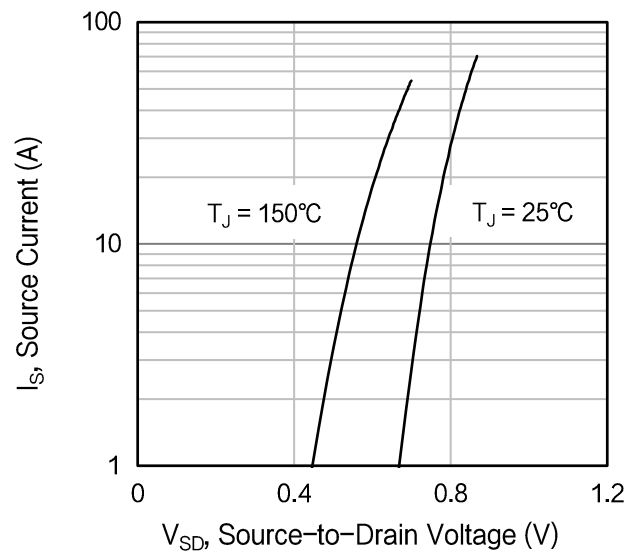


Figure 3. Drain Current vs. Temperature

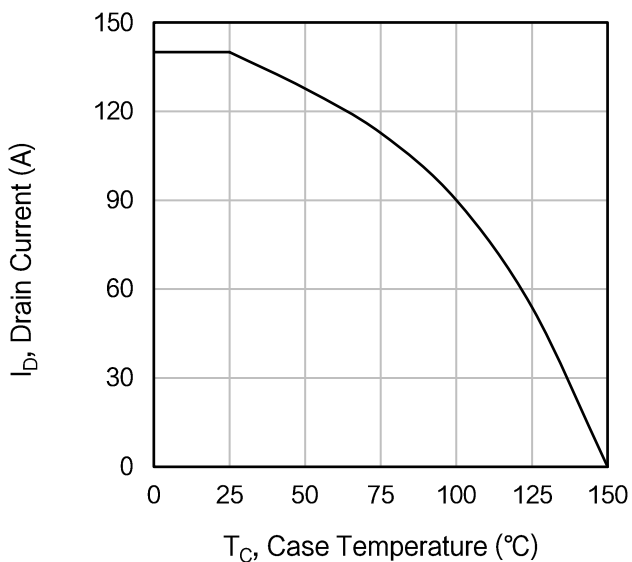


Figure 4. Transfer Characteristics

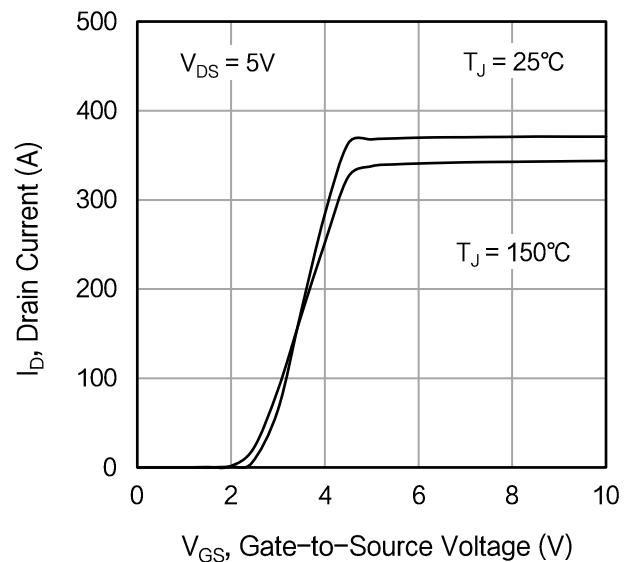


Figure 5.  $BV_{DSS}$  Variation vs. Temperature

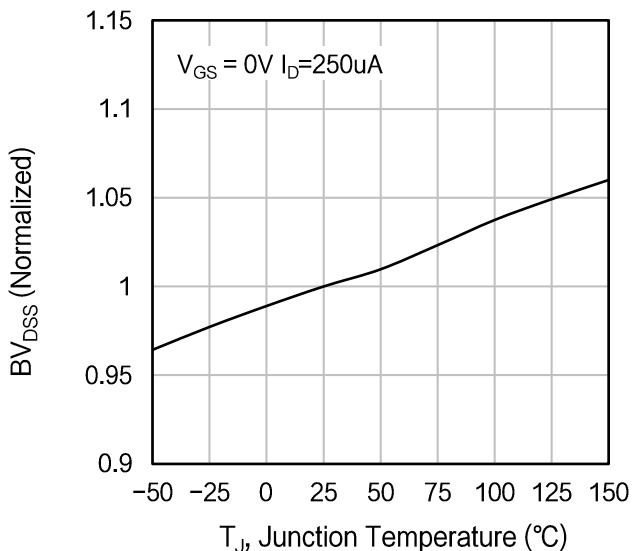
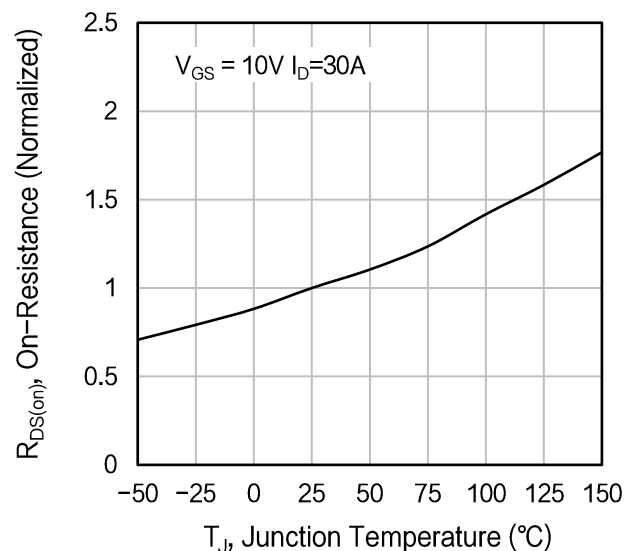


Figure 6. On-Resistance vs. Temperature



Typical Characteristics  $T_J = 25^\circ\text{C}$ , unless otherwise noted

Fig.7 Threshold Voltage vs. Temperature

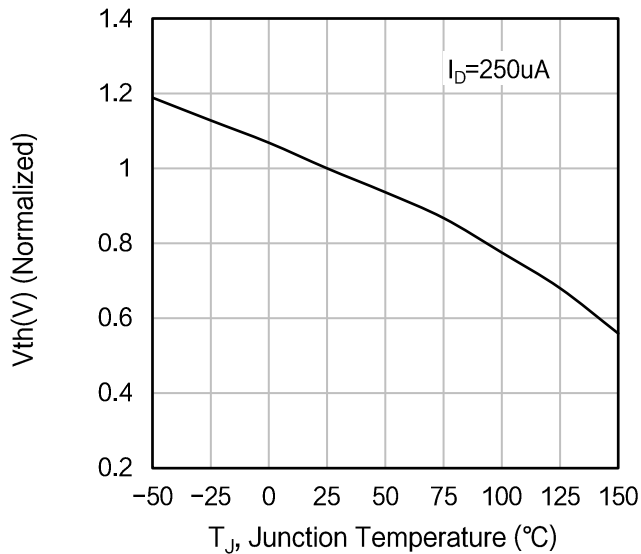


Figure 8. On-Resistance vs. Drain Current

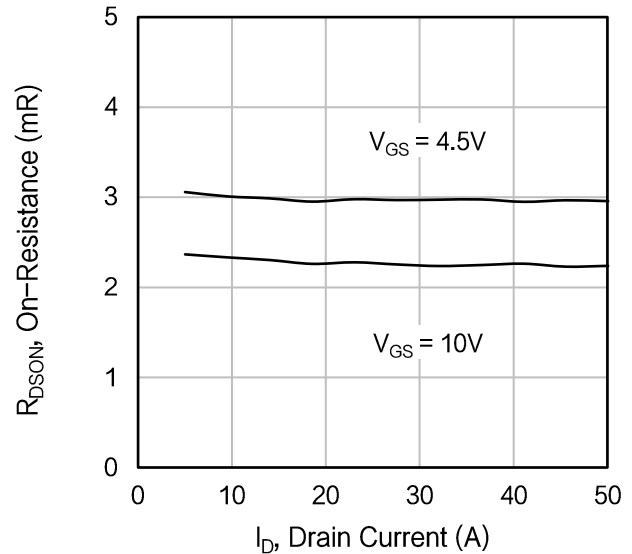


Figure 9. Capacitance

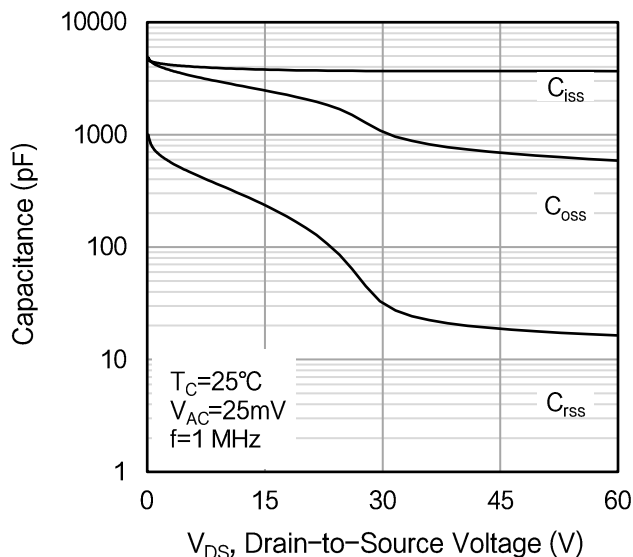


Figure 10. Gate Charge

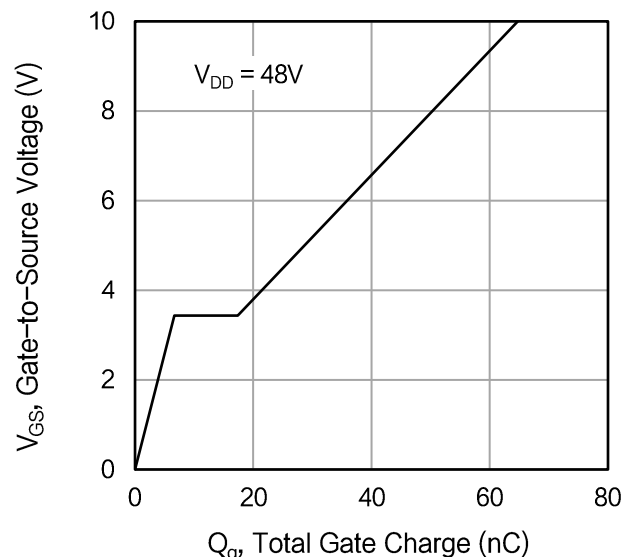


Figure 11. Safe Operating Area

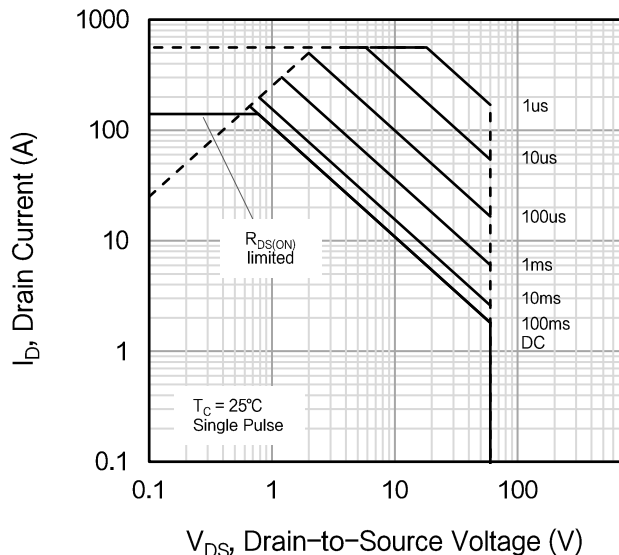


Figure 12. Transient Thermal Impedance

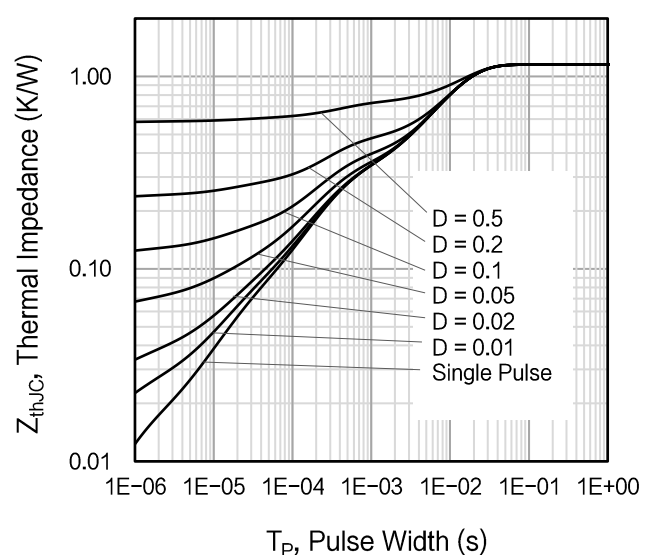


Figure A: Gate Charge Test Circuit and Waveform

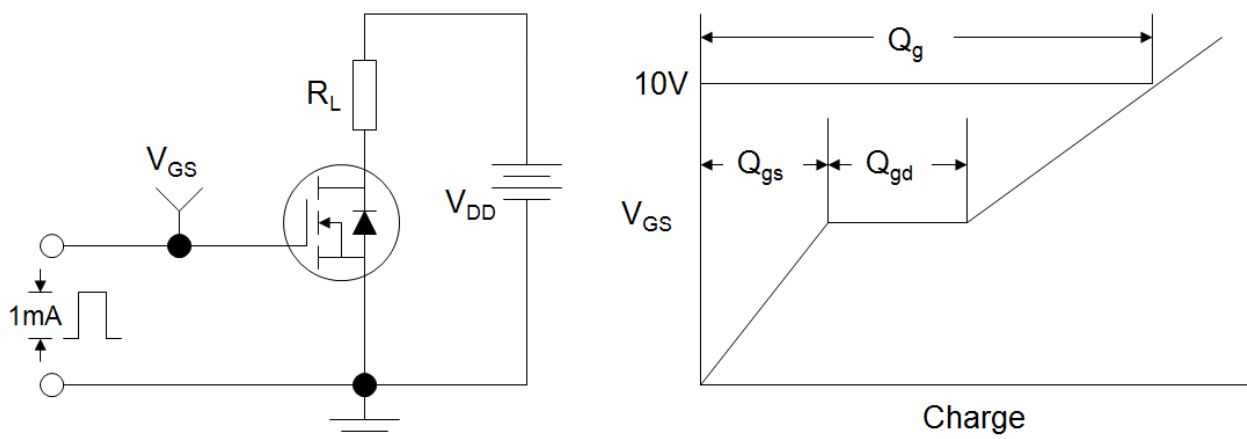


Figure B: Resistive Switching Test Circuit and Waveform

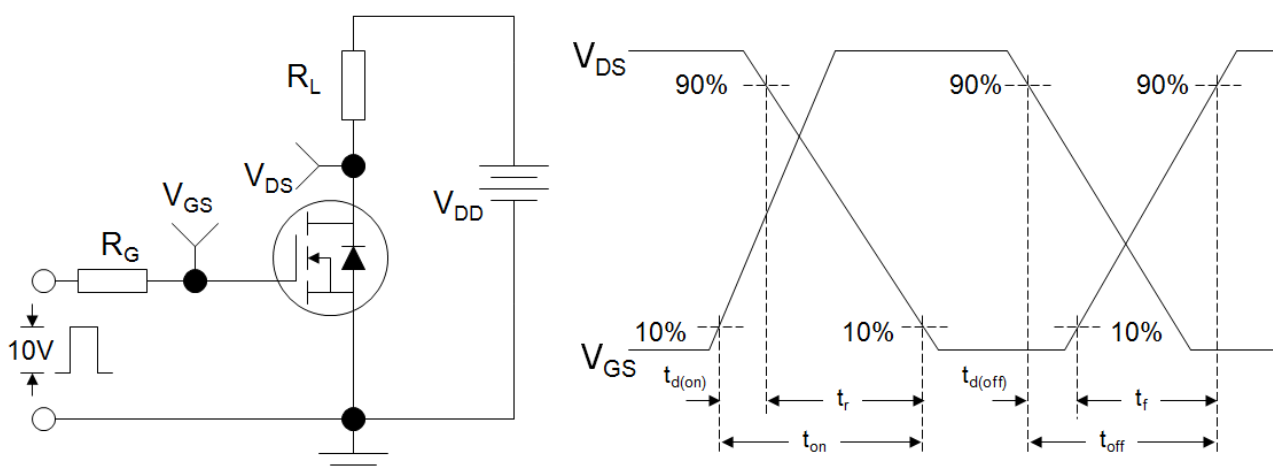
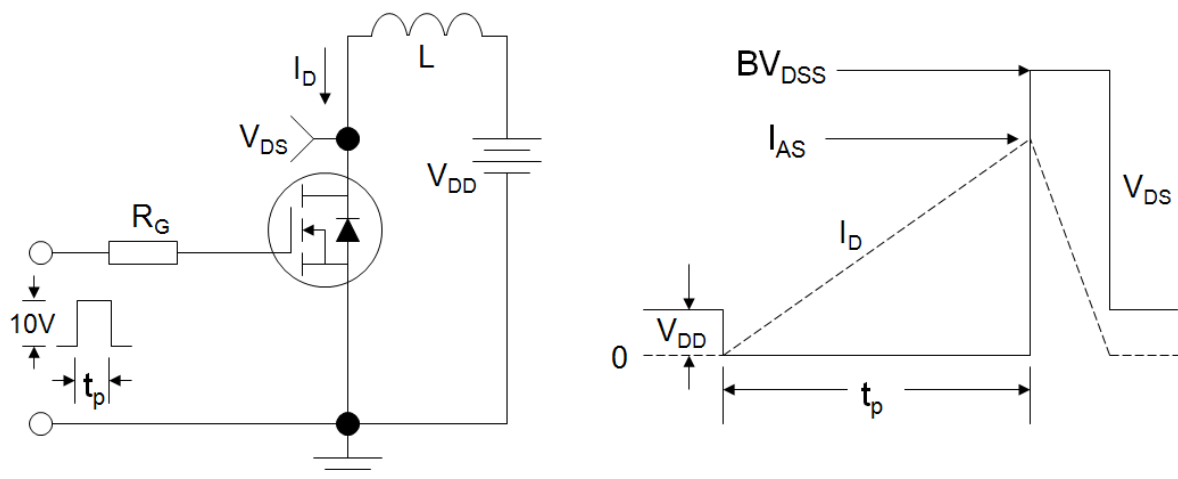
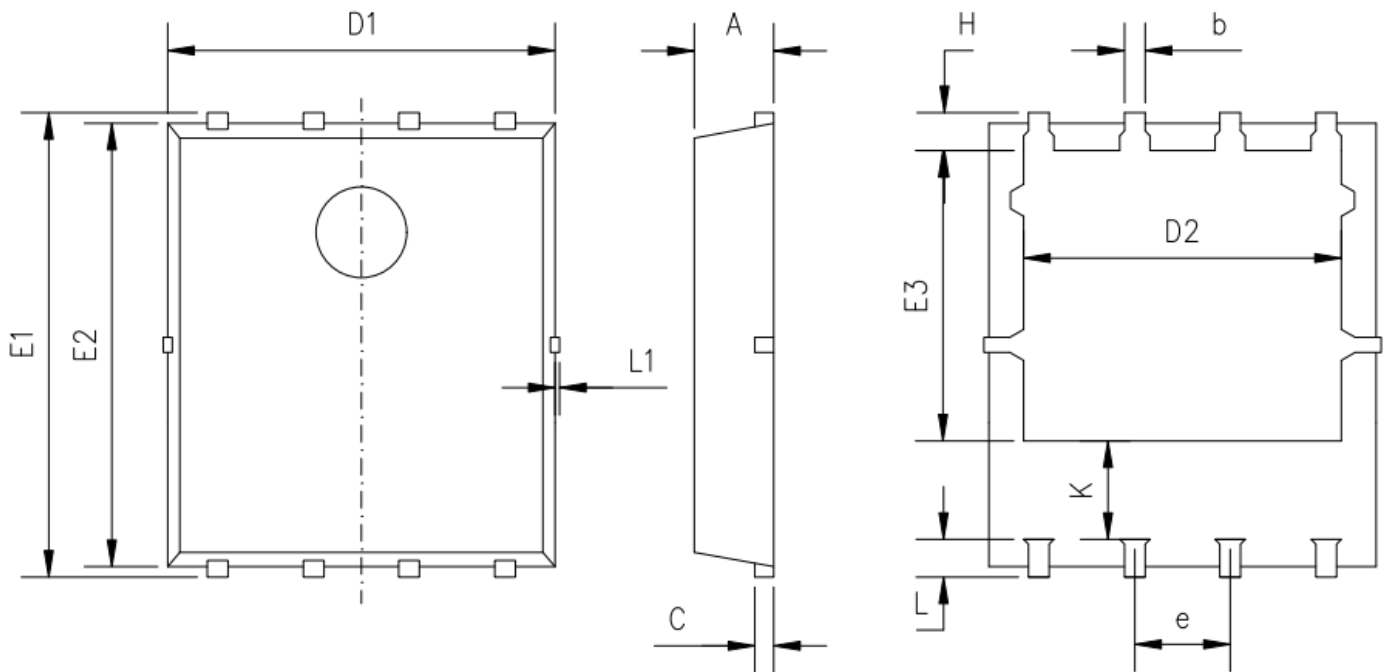


Figure C: Unclamped Inductive Switching Test Circuit and Waveform



PDFN5 × 6



SYMBOLS	MILLIMETERS	
	MIN	MAX
A	0.90	1.20
b	0.25	0.50
C	0.10	0.35
D1	4.80	5.40
D2	3.72	4.25
e	1.17	1.37
E1	5.90	6.35
E2	5.60	6.06
E3	3.33	3.92
H	0.40	0.71
L	0.30	0.84
L1	0.00	0.15
K	1.00	1.50

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